

SPECIFICATION



Mass Product

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1. Product Description

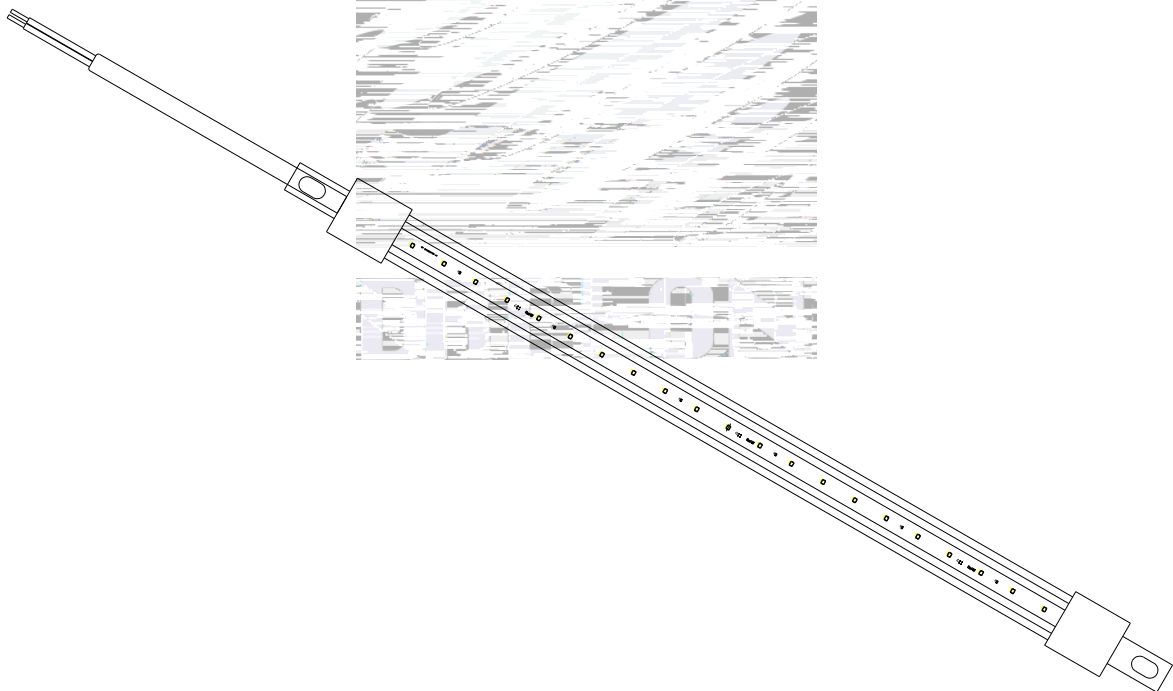
high reliability and high safety;

2835 LED Package, high lighting efficiency, low heat, without Mercury, belong to the environmental protection cold light source;

The protection of the lamp is up to IP67, with beautiful appearance, no fouling situation.

Designed for normal and low temperature refrigeration walk-ins and display case applications;

Ideal for C-Stores, Grocery, and Big Box Retailers.



2.Product Specification

2.1 Optical-electrical Characteristics(Absolute Maximum Ratings At Ts=25)

Tab.2-1Optical-electrical Characteristics

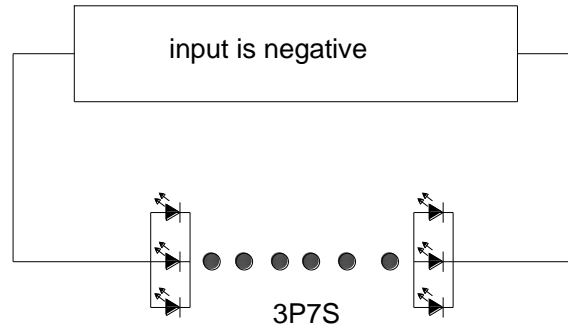
Refond PN	Customer PN	Current	Voltage(V)	Power(W)	Module LM	
		mA			Min	Max
		Typ	Typ	Typ		
RF-MTB652T03-A1 6000-6500K	-	125	24	3 8%	375	420
Color Rendering Index		(V)Test condition		Typ		
		24		24		
				5		

Absolute Maximum Ratings at Ts=25°C

Parameter	Symbol	Rating	Units
Forward Current	I _F	125 8%	mA
Peak Forward Current	I _{FP}	165	mA
Reverse Voltage	V _R	5	V
Electrostatic Discharge	E _{SD}	2000	V
Operating Temperature	T _{OPR}	-40 ~ +85	
Storage Temperature	T _{STG}	-40 ~ +100	
unction temperature	T _J	115	

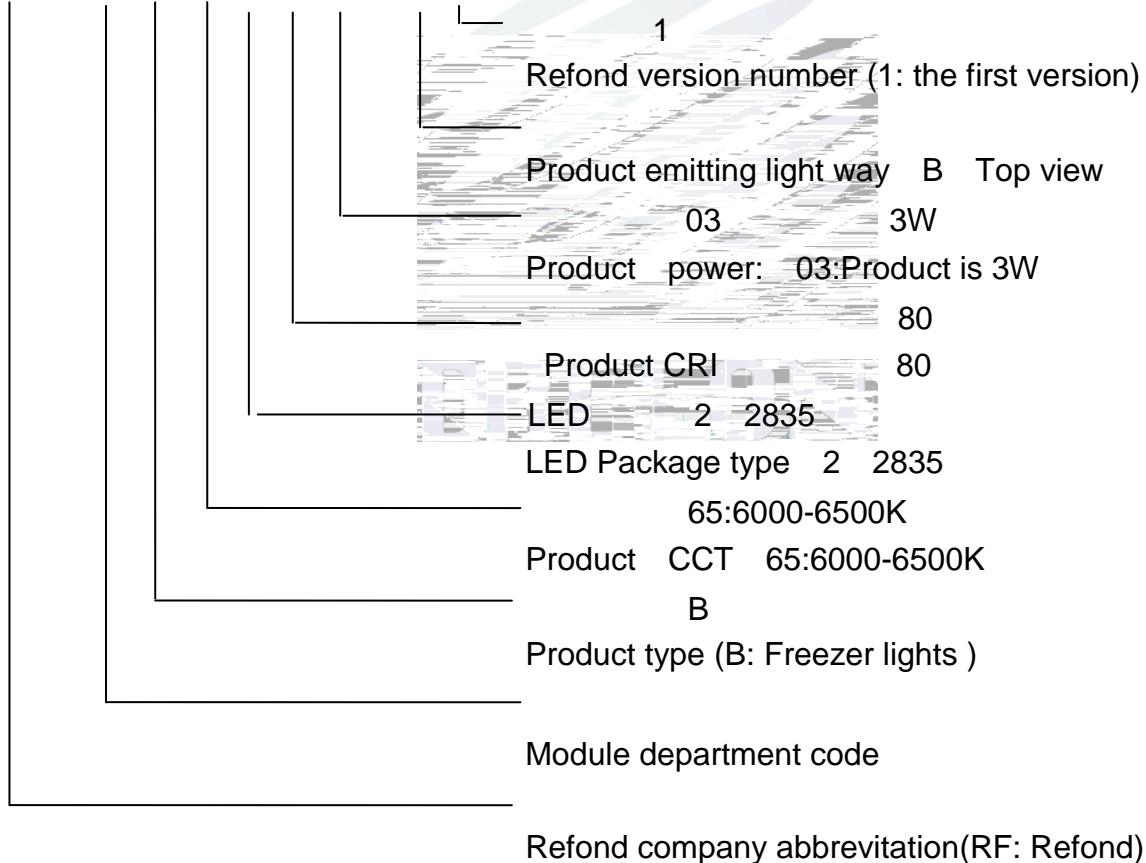
2.2 Product Schematic And Interface Definition

Fig.2-2 Product connection



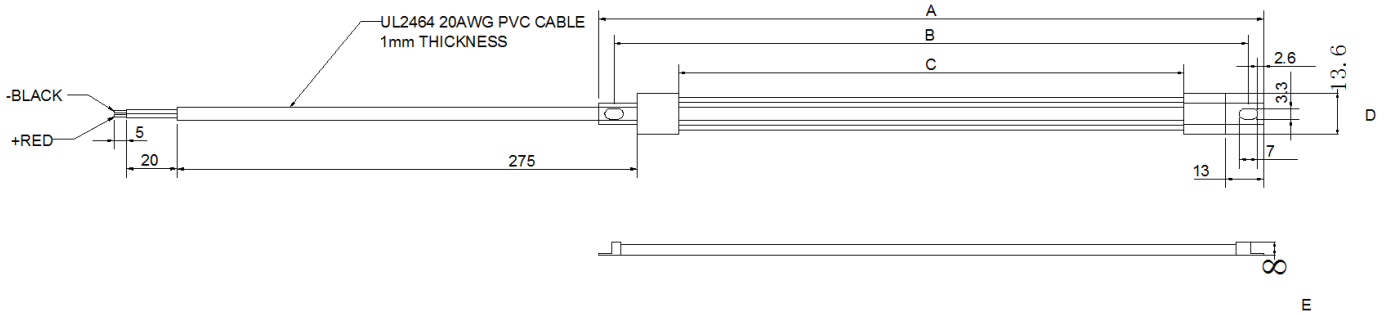
2.3 Product Module rule of naming :

RF MT B 65 2 T 03 B 1



3. Product Specification

3.1 Outline Dimension



	Dimension
A	629 5mm
B	616 5mm
C	580 5mm
D	13.6 1mm
E	8 1mm



5. Product Materials Performance Test And Method At Ta=25

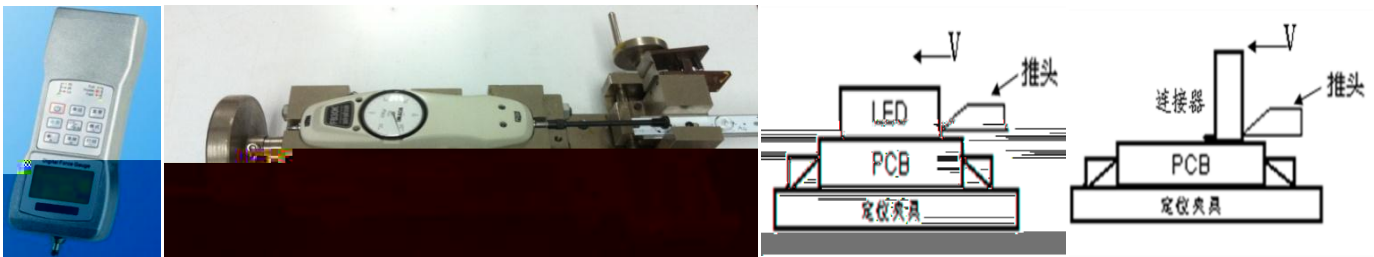
Tab 5-1 Light Bar Materials Performance Test And Method Ta=25

Test Item	Test Conditions	Test Methods
LED Optical-electrical Characteristics LED	Compliance With Specifications/	Integrating Sphere/
Connector Pull Force/		Notes/
LED Push & Pull Force LED		
LED Welding Standards LED	Offset Specifications/ X Shift /X Y Shift/ Y Angle/	

Notes

Fig 5-1 Push & Pull Test Equipment

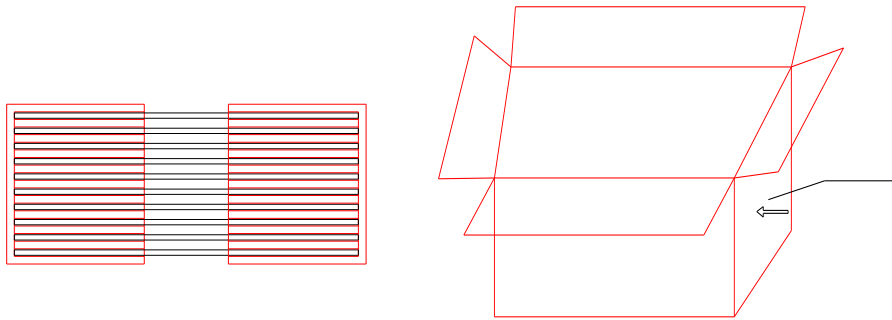
Fig 7-2 Push & Pull Test Method



6.Packing Criterion

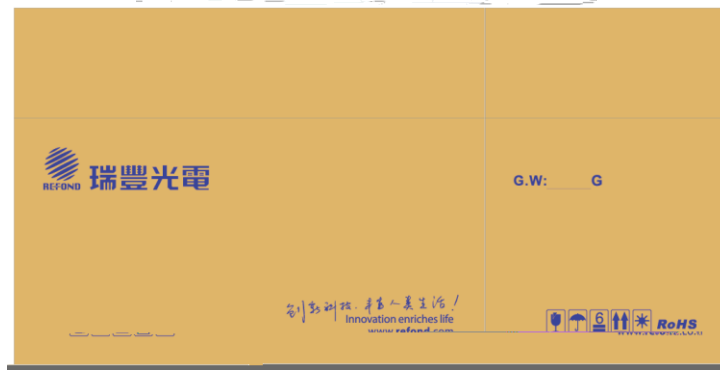
6.1 Package Diagram /

Fig 8-1 Package Diagram /



6.2 Carton silk printing/

REFOND LOGOPay attention to identify



6.3 Label Form Specification/

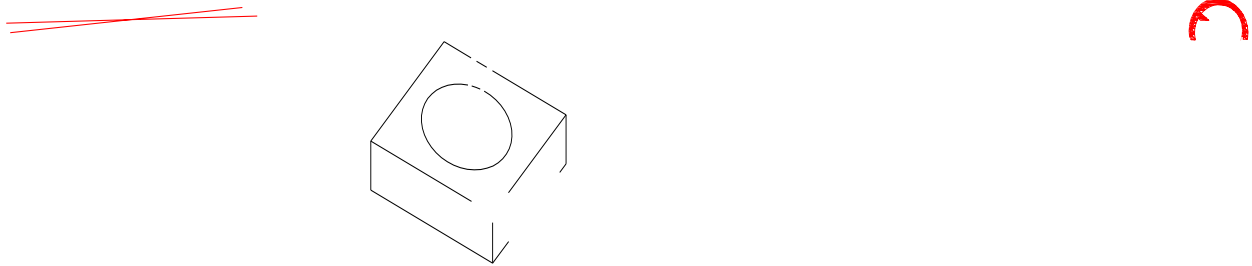

深圳市瑞豐光電子股份有限公司
 REFOND SHENZHEN REFOND OPTOELECTRONICS CO.,LTD.

customer PN			
/P.N			
/BIN CODE		/LM	
/VF		/CCT	
		/QTY	
/N.W		/DATE	

7. Handling Precautions



(4) Handle the component along the side surface by using forceps or appropriate tools; do not directly touch or Handle the silicone lens surface, it may damage the internal circuitry.



(5) In designing a circuit, the current through each LED cannot be exceeded the absolute maximum rating specified for each LED. In the meanwhile, resistors for protection should be applied, otherwise slight voltage shift will cause big current change, burn out may happen. The driving circuit must be designed to allow forward voltage only when it is ON or OFF. If the reverse voltage is applied to LED, migration can be generated resulting in LED damage.

(6) Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Color change and so on. Please consider the heat generation of the LEDs when making the system design. LED

(7) Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust, requiring special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components. Refond suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause

damage to the LED.

(8) Similar to most Solid state devices; LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS).

9>.NO warping or twisting the Light Bar more than 10°. Forbidding holding the LED part or connector part when handling.



(10) Other points for attention, please refer to our relevant information.



Version History/

Date	Revisor	Version	Verifier	Remarks
2021-4-13		E/0		The first edition





Declare

This specification is written both in English and in Chinese and the latter is formal.